

September 2010

# FDI8442\_F085

# N-Channel PowerTrench® MOSFET 40V, 80A, 3.1m $\Omega$

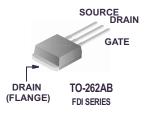
### **Features**

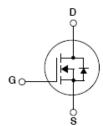
- Typ  $r_{DS(on)} = 2.3m\Omega$  at  $V_{GS} = 10V$ ,  $I_D = 80A$
- Typ  $Q_{g(10)} = 181nC$  at  $V_{GS} = 10V$
- Low Miller Charge
- Low Q<sub>rr</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant



# **Applications**

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter / Alternator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems





# **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	±20	<b>V</b>
	Drain Current Continuous (T <sub>C</sub> <158°C, V <sub>GS</sub> = 10V)	80	
I <sub>D</sub>	Drain Current Continuous (T <sub>amb</sub> = 25°C, V <sub>GS</sub> = 10V, with R <sub>θJA</sub> = 62°C/W)	23	Α
	Pulsed	See Figure 4	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	720	mJ
	Power Dissipation	254	W
$P_{D}$	Derate above 25°C	1.7	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to +175	οС

### **Thermal Characteristics**

$R_{\theta,JC}$	Thermal Resistance Junction to Case	0.59	°C/W	
R <sub>e.IA</sub>	Thermal Resistance Junction to Ambient	(Note 2)	62	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDI8442	FDI8442_F085	TO-262AB	Tube	N/A	50 units

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

**Parameter** 

Off Ch	Off Characteristics						
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V	
	Zara Cata Valtaga Drain Current	V <sub>DS</sub> = 32V	-	-	1	цΑ	
IDSS	Zero Gate Voltage Drain Current	$V_{GS} = 0V$ $T_J = 150^{\circ}C$	-	-	250	μА	
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA	

**Test Conditions** 

Min

Тур

Max

Units

### **On Characteristics**

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	2.9	4	V
	$I_D = 80A, V_{GS} = 10V$	-	2.3	3.1		
r <sub>DS(on)</sub>	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V,$ $T_A = 175^{\circ}C$	-	3.9	5.3	mΩ

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance		V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		12200	-	pF
C <sub>oss</sub>	Output Capacitance				1040	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	I = IIVIIIZ			640	-	pF
$R_{G}$	Gate Resistance	$V_{GS} = 0.5V, f = 1MHz$		ı	1.0	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		ı	181	235	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	$V_{DD} = 20V$	ı	23	30	nC
$Q_{gs}$	Gate to Source Gate Charge		I <sub>D</sub> = 80A	ı	49	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau		$I_g = 1mA$	ı	26	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	41	-	nC

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

Symbo	Parameter Parameter	Test Conditions	Min	Тур	Max	Units
Switch	ing Characteristics					
t <sub>(on)</sub>	Turn-On Time		-	-	62	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	19.5	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 20V, I_D = 80A$	-	19.3	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10V$ , $R_{GS} = 2\Omega$	-	57	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	17.2	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	118	ns

### **Drain-Source Diode Characteristics**

V <sub>SD</sub> Source to Drain Diode Voltage	Occurs to Ducin Diada Vallage	I <sub>SD</sub> = 80A	-	0.9	1.25	V
	I <sub>SD</sub> = 40A	-	0.8	1.0	V	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 75A, di/dt = 100A/μs	-	49	64	ns
$Q_{rr}$	Reverse Recovery Charge	I <sub>F</sub> = 75A, di/dt = 100A/μs	-	70	91	nC

1: Starting T<sub>J</sub> = 25°C, L = 0.35mH, I<sub>AS</sub> = 64A 2: Pulse width = 100s.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

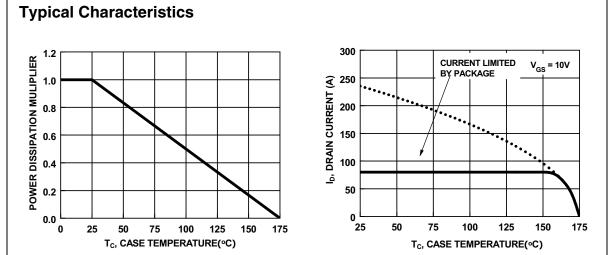


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs
Case Temperature

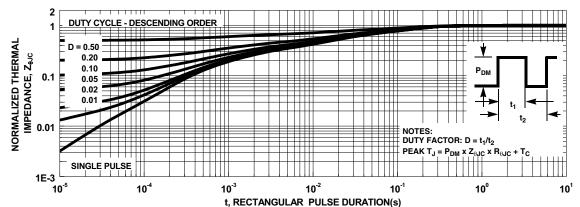


Figure 3. Normalized Maximum Transient Thermal Impedance

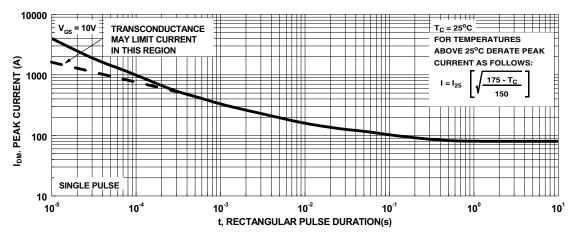


Figure 4. Peak Current Capability

# **Typical Characteristics**

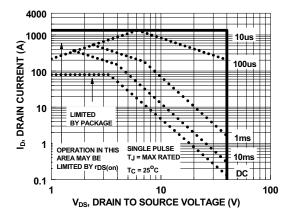
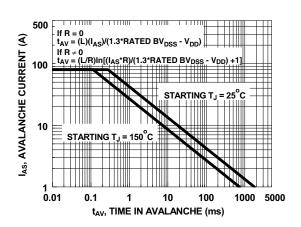


Figure 5. Forward Bias Safe Operating Area Figure 6. Unclamped



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

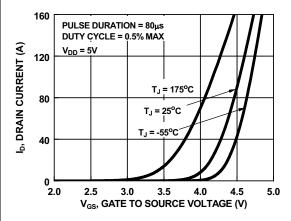


Figure 7. Transfer Characteristics

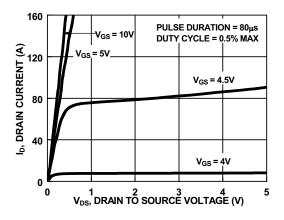


Figure 8. Saturation Characteristics

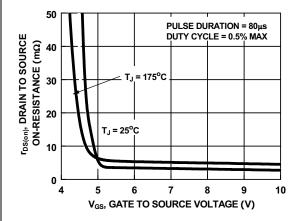


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

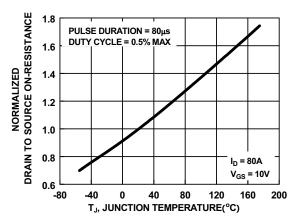


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

# **Typical Characteristics**

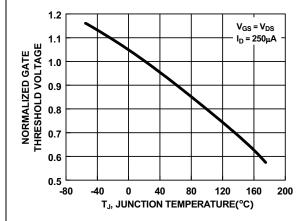


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

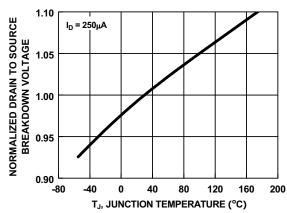


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

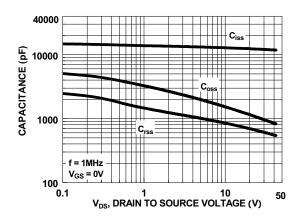


Figure 13. Capacitance vs Drain to Source Voltage

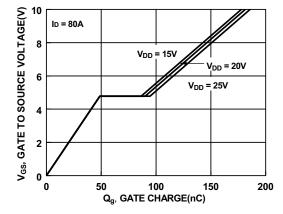


Figure 14. Gate Charge vs Gate to Source Voltage





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